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RF360 Europe GmbH

# **Data sheet**

SAW RF filter Automotive telematics Beidou; GPS; GLONASS

Series/type:B2618Ordering code:B39162B2618P810

Date:November 05, 2018Version:2.0

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SAW RF filter B2618 Data sheet

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# 1 Application

- Low-loss RF single filter for GPS + BEIDOU + GLONASS application
- Simultaneous usage of GPS, BEIDOU and GLONASS band
- High out of band selectivity
- No matching network required for operation at 50 Ω

# 2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 1: -40 °C to +125 °C)



**Figure 1:** Picture of component with example of product marking.

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#### 3 Package



Pad and pitch tolerance ±0.05

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number





Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

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■ 2, 3, 5 Ground

Pin configuration



# 5 Matching circuit



Figure 3: Schematic of matching circuit. No external matching components required.

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#### 6 Characteristics

Temperature range for specification	T <sub>SPEC</sub>	= −30 °C +85 °C
Input terminating impedance	Z <sub>N</sub>	= 50 Ω
Output terminating impedance	Z <sub>OUT</sub>	= 50 Ω

Characteristics			min. for $T_{_{\rm SPEC}}$	<b>typ.</b> @ +25 °C	max. for $T_{_{\rm SPEC}}$	
Center frequency		f <sub>c</sub>		1582.47		MHz
Maximum insertion attenuation		α <sub>max</sub>				
	1559.052 1563.144	MHz	_	1.4	1.8	dB
	1574.42 1576.42	MHz	_	0.9	1.4	dB
	1597.55 1605.89	MHz	_	1.4	1.8	dB
Maximum VSWR		VSWR <sub>max</sub>				
@ input port	1559.052 1563.144		_	1.7	2.0	
	1574.42 1576.42	MHz	_	1.2	1.8	
	1597.55 1605.89	MHz	_	1.5	1.9	
@ output port	1559.052 1563.144	MHz	_	1.7	2.0	
	1574.42 1576.42			1.2	1.8	
	1597.55 1605.89	MHz	_	1.5	1.9	
Minimum attenuation		$\alpha_{_{min}}$				
	50 915	MHz	49	52	_	dB
	915 1463	MHz	42	47	_	dB
	1710 1850	MHz	34	40		dB
	1850 1990	MHz	38	43	—	dB
	1990 2300	MHz	37	40	—	dB
	2300 2400	MHz	42	46	—	dB
	2400 2500	MHz	43	46	—	dB
	2500 2700	MHz	41	43	_	dB
	2700 3000	MHz	38	41		dB
	3000 6000	MHz	25	28		dB
Group delay ripple		$\Delta  au_{ m var}$				
	1597.55 1605.89	MHz	_	4.0	12	ns <sup>1)</sup>

<sup>1)</sup> Measured with an aperture of 2MHz.

#### 7 Maximum ratings

Operable temperature	$T_{\rm OP} = -40 ^{\circ}{\rm C} \dots +125 ^{\circ}{\rm C}$	
Storage temperature	$T_{\rm STG}^{(1)} = -40 ^{\circ}{\rm C} \dots +125 ^{\circ}{\rm C}$	
DC voltage	$ V_{\rm DC} ^{2)} = 0 V$	
Input power	P <sub>IN</sub>	
@ input port: 777 915 MHz	27 dBm	Continuous wave for 5000 h @ 55 °C.
@ input port: 1710 2200 MHz	25 dBm	Continuous wave for 5000 h @ 55 °C.

<sup>1)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.

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# 8 Transmission coefficient

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Figure 4: Attenuation .

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### 9 Reflection coefficients

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# 10 Packing material

### 10.1 Tape



User direction of unreeling

**Figure 7:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

 $\begin{array}{c} A_0 \\ B_0 \\ 1.22 \pm 0.05 \text{ mm} \\ D_0 \\ 1.55 \pm 0.05 \text{ mm} \\ D_1 \\ 0.55 \pm 0.1 \text{ mm} \\ E_1 \\ 1.75 \pm 0.1 \text{ mm} \end{array}$ 

E2	6.25 mm (min.)
F	3.5±0.05 mm
G	-
$K_0$	0.6±0.05 mm
P <sub>0</sub>	4.0±0.1 mm

P <sub>1</sub>	2.0±0.1 mm
$P_2$	2.0±0.05 mm
Т	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Table 1: Tape dimensions.

\_



# 10.2 Reel with diameter of 180 mm









Figure 10: Drawing of folding box for reel with diameter of 180 mm.

# 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

Type number:

The 4 digit type number of the ordering code, is encoded by a special BASE32 code into a 3 digit marking.	
levice =>	in decimal code. <b>1234</b>
=	1234
	levice

Lot number:

The last 5 digits of the lot number,e.g.,12345,are encoded based on a special BASE47 code into a 3 digit marking.12345,

Example of decoding	lot number marking	on device
---------------------	--------------------	-----------

5UY	=>	12345
<b>5</b> x 47 <sup>2</sup> + <b>27 (=U)</b> x 47 <sup>1</sup> + <b>31 (=Y)</b> x 47 <sup>0</sup>	=	12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	К
4	4	20	М
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal	Base47	Decimal	Base47
value	code	value	code
0	0	24	R
1	1	25	S
2	2	26	Т
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	Х
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	В	35	f
12	С	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	Н	41	١
18	J	42	?
19	К	43	{
20	L	44	}
21	М	45	<
22	N	46	>
23	Р		

in decimal code.

**Table 2:** Lists for encoding and decoding of marking.

# 12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

# 13 ESD protection of SAW filters

SAW filters are Electro Static Discharge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, "ESD matching" has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended "ESD matching" topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3<sup>rd</sup> order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.



Figure 12: MLC varistor plus ESD matching.



matching.

In cases where minor ESD occur, following simplified "ESD matching" topologies can be used alternatively.



**Figure 14:** 3<sup>rd</sup> order high-pass structure for basic ESD protection.

In all three figures the shunt inductor  $L_{p2}$  could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: **"ESD protection for SAW filters".** This report can be found under <u>www.rf360jv.com/rke</u>. Click on "Applications Notes".

# 14 Annotations

# 14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

# 15 Cautions and warnings

# 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

# 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

# 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

# 15.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

# Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### **Projection method**

Unless otherwise specified first-angle projection is applied.

# 16 Important notes

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